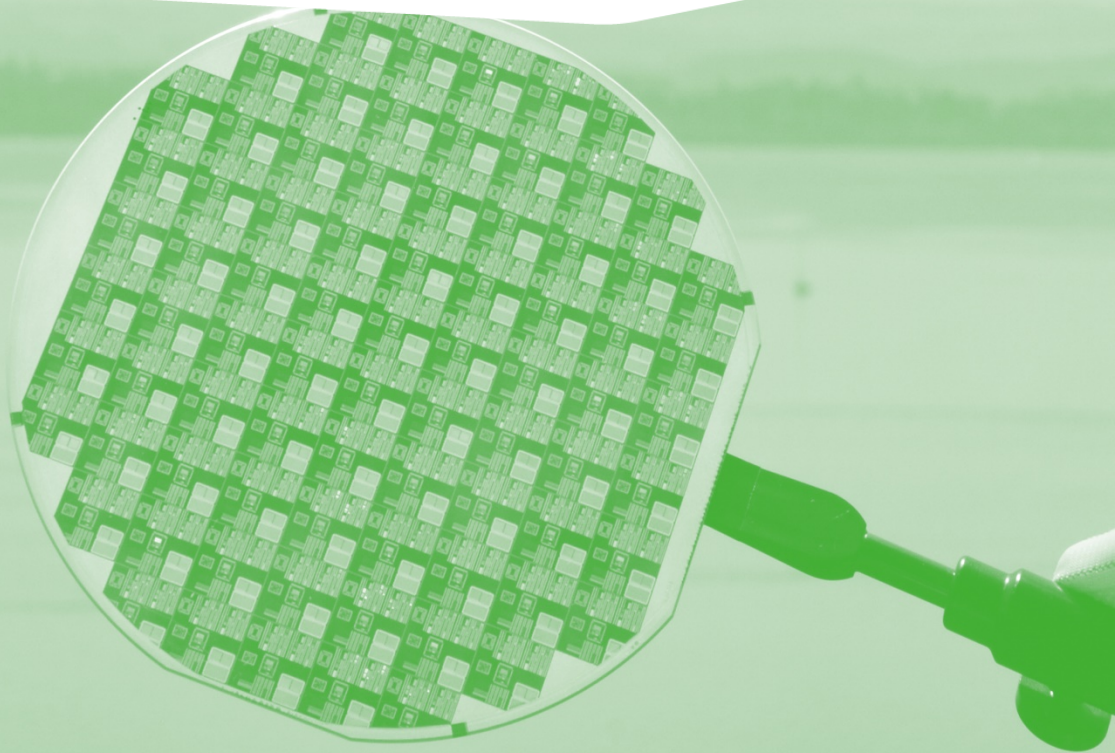


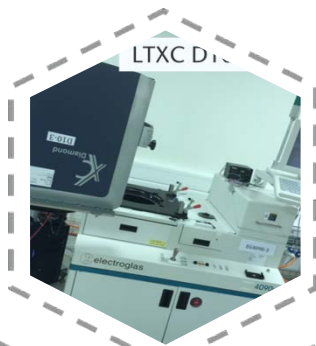


MUCH MORE THAN ASIC TEST

ATE AND CMOS IMAGERS



ATE AND PROBERS dedicated to CMOS imager probing



LTXC D10 ATE mixed signal

D10 configuration: (2x) DPIN96,VIS16,DPS,
MultiWave, DIBU



EG4090 Prober

8 inches prober (Dark & clean set-up)



Ex3000 Accretec prober

12 inches prober (Dark light and clean set-up)

From “standard” to custom solutions

Test Solution = HW + SW specific development

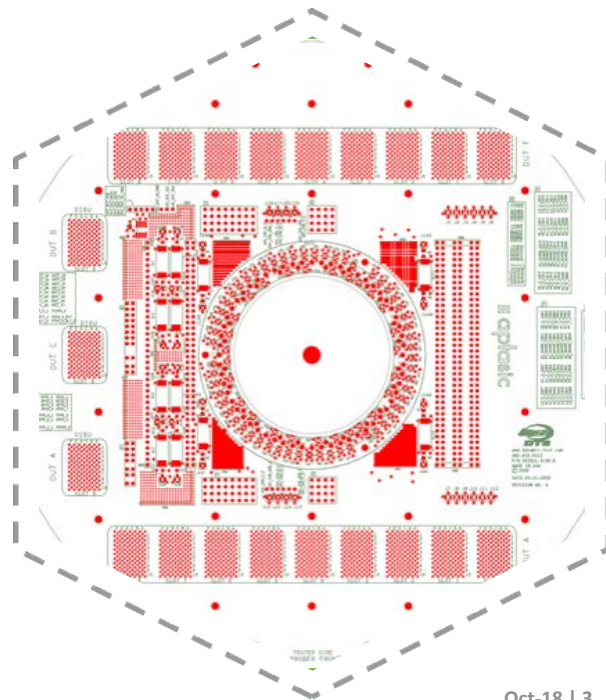
Standard HW development by Aptasic :

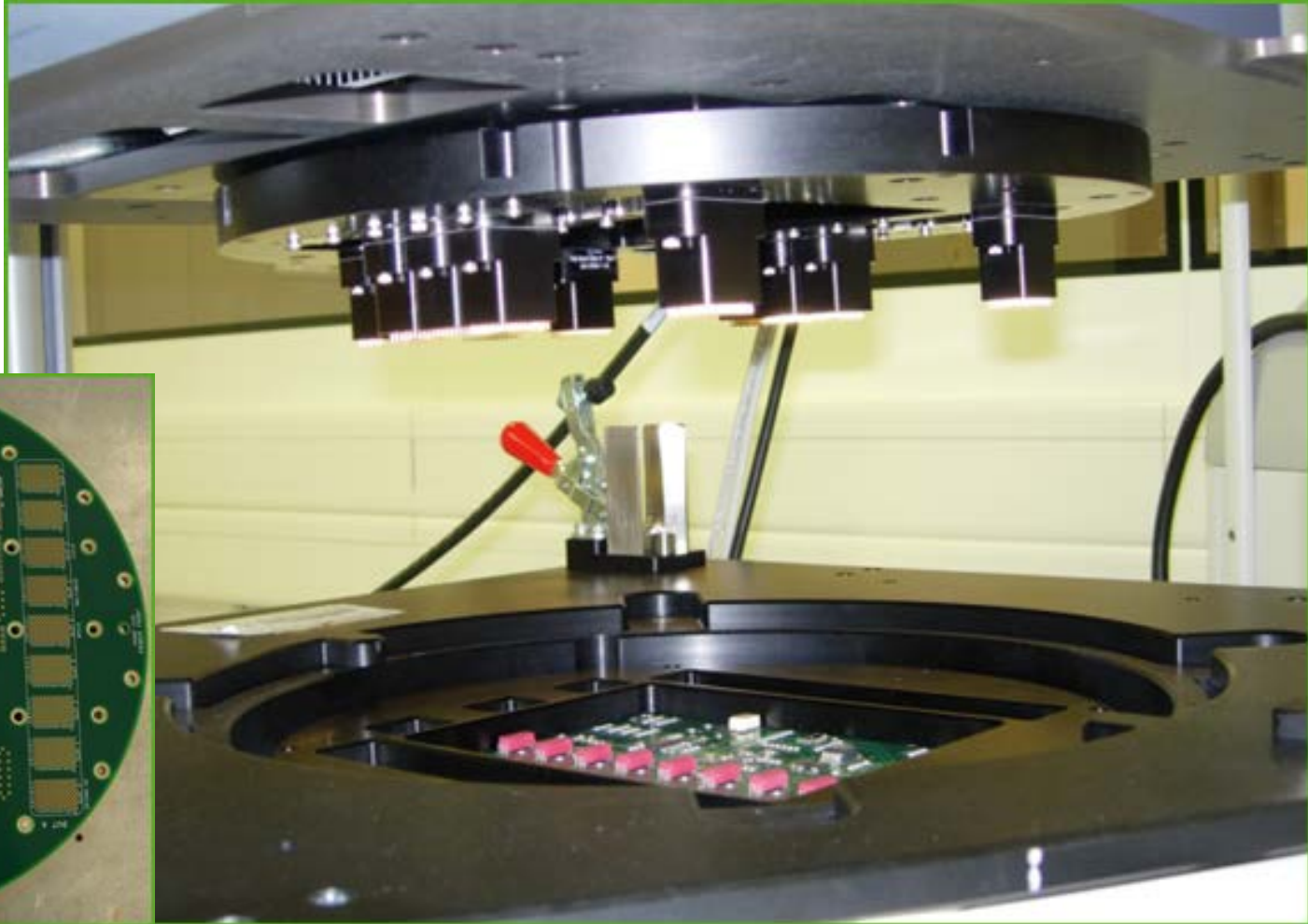
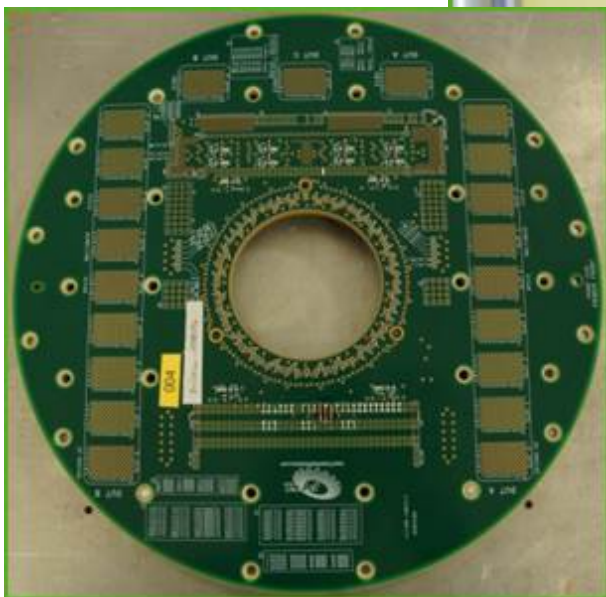
Standard Load-Board 84 signals

SW developed by Aptasic:

High level language code (C/C++)

Low investment - short lead time for first tested Silicon





From “standard” to custom solutions

84 pin HW ProbeCard

Compatible with former concept

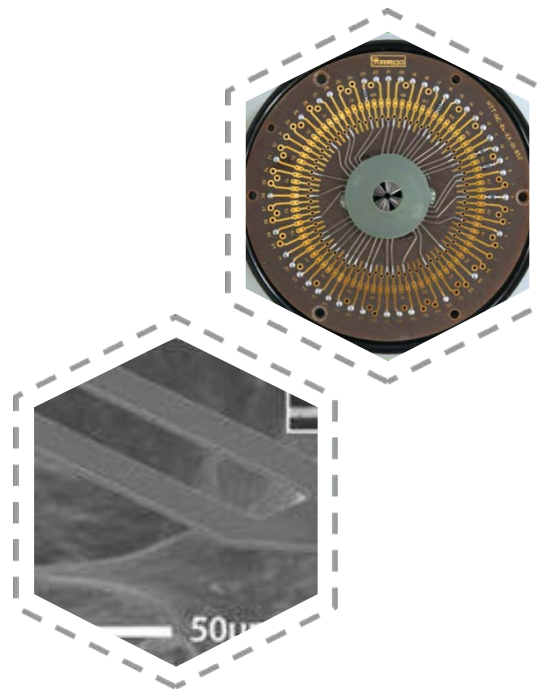
Used for wafer probing

One needle to contact each pad or solder bump
(WLCSP)

Spider with cantilever or vertical needles to ensure precise position of each needle

Fixed on the main Load-Board

Project specific



From “standard” to custom solutions

84 pin HW DUT-board

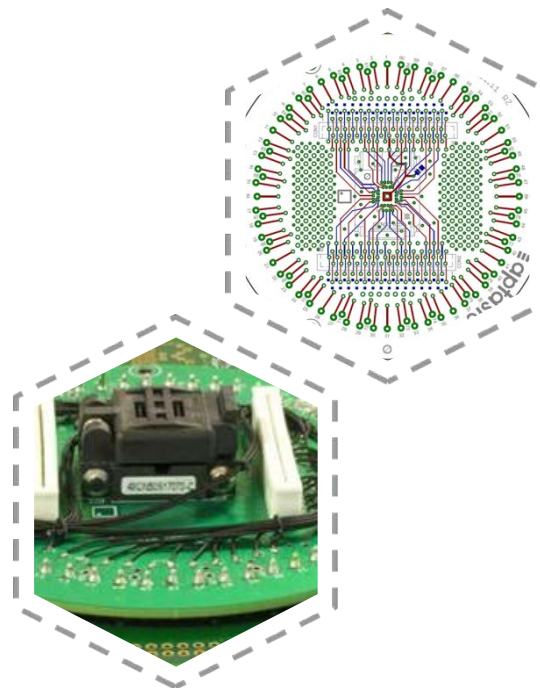
Compatible with Loadboard concept

Used for manual test

ZIF socket soldered on it to ensures contact with DUT

Flat cable connectors

Fixed on the main LoadBoard



From “standard” to custom solutions

Dedicated Handler Board

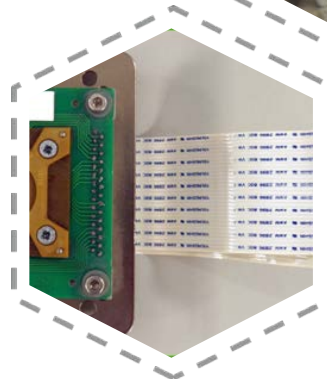
Automatic DUT contact block

PCB contains the footprint for the test socket

Interfaces with the handler robot

Precise position on the handler

Project specific



CMOS IMAGERS TEST CONCEPT

Layout

Test flow

Structural tests

Functional tests

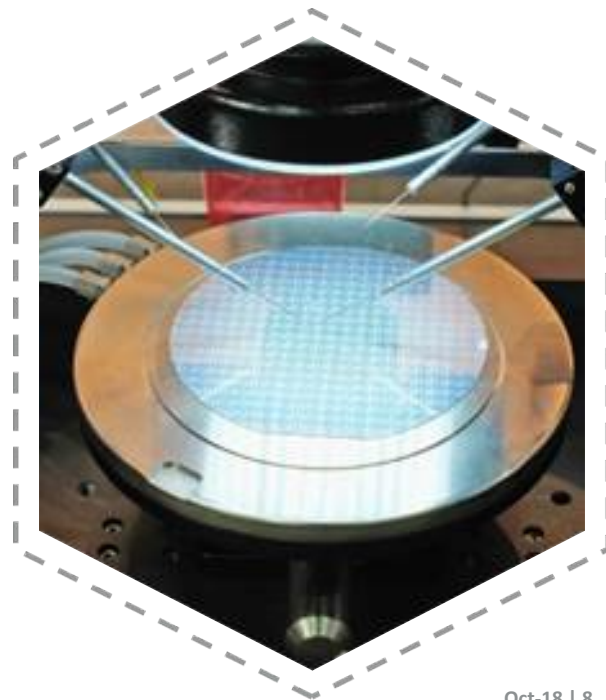
Performance tests

HW interfaces

Load-board (Test Adapter Interface for imagers)

Probe-Card (wafer test)

Light source (variable light flow)





CMOS IMAGERS ILLUMINATION INTEGRATION

Custom illumination integrated to Loadboard

Light Source Specifications and calibration

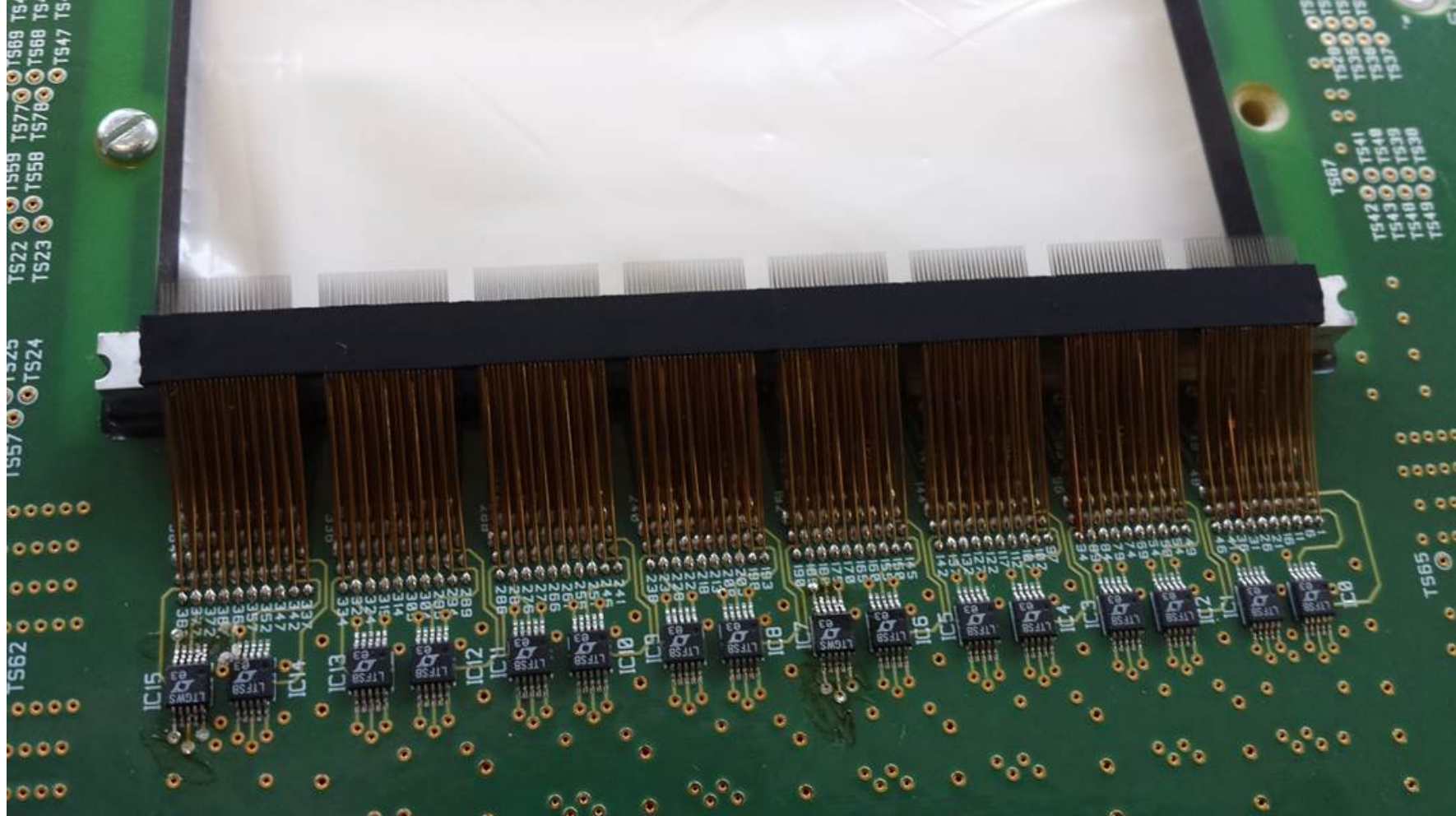
Intensity and Wavelength Control

Uniformity (Noise reduction)

Large spectrum

Diffuser

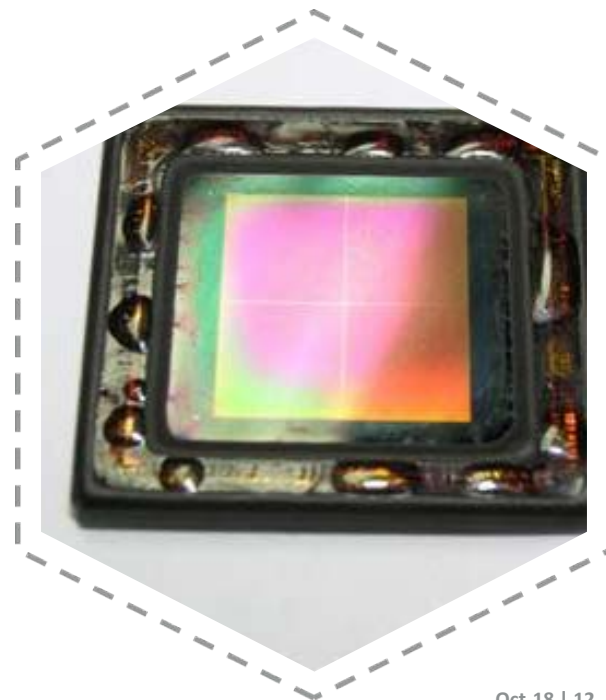




CMOS IMAGERS STRUCTURAL / FUNCTIONAL TEST

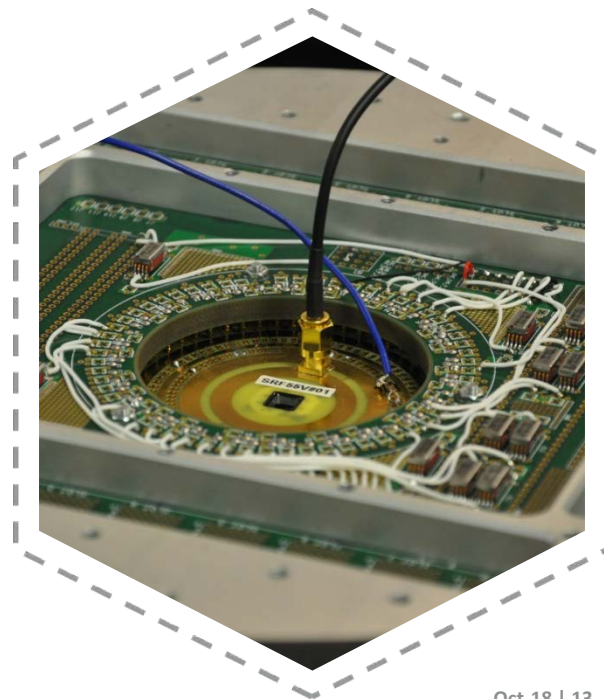
Test descriptions

1. Signal pad Opens-and-shorts and leakage current tests
2. Basic power draw at hardcoded defaults
3. Serial control register (SPI port) test
4. DACs test
5. Digital control signals test
6. Power shorts on array columns test
7. Test pixels test
8. Power draw vs. IBias DAC settings
9. Functional evaluation
 - Video Amp gain selection and column binning
 - S/H time constant selection
 - Dynamic gain switching
 - Pixel gain selection functionality
 - Row binning



CMOS IMAGERS PERFORMANCE EVALUATION

10. Performance evaluation
 - Pixels offset and electronic noise
 - Pixels leakage current
 - Video buffer electronic noise
 - Sensitivity, Saturation levels and saturation artifacts
 - Linearity
 - Video amplifier settling
 - Crosstalk, non-uniformity and other image artifacts over signal range and steps in image
11. Defective pixels, row segments, column segments, rows, columns
 - Test results reporting
 - Default acquisition timing sequence
 - Correlated double sampling



Take away



- Structural and performance test on Wafer and package verification
- Hardware concept easy to deploy
- Test flow tailored to your coverage requirement

... up to 12 inches Wafers!

THANKS FOR YOUR ATTENTION

